



2N7002BKW

60 V, 310 mA N-channel Trench MOSFET

17 October 2024

Product data sheet

1. General description

N-channel enhancement mode Field-Effect Transistor (FET) in a small SOT323 (SC-70) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Logic-level compatible
- Very fast switching
- Trench MOSFET technology
- ESD protection up to 2 kV
- AEC-Q101 qualified

3. Applications

- Relay driver
- High-speed line driver
- Low-side load switch
- Switching circuits

4. Quick reference data

Table 1. Quick reference data

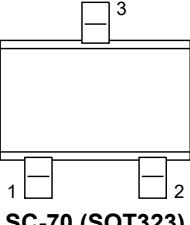
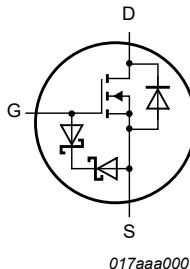
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V _{DS}	drain-source voltage	T _{amb} = 25 °C	-	-	60	60	V
V _{GS}	gate-source voltage		-20	-	20	20	V
I _D	drain current	V _{GS} = 10 V; T _{amb} = 25 °C	[1]	-	-	310	mA
Static characteristics							
R _{DSon}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 500 mA; t _p ≤ 300 µs; δ ≤ 0.01; T _j = 25 °C		-	1	1.6	Ω

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm².

勝特力電材超市-龍山店 886-3-5773766
勝特力電材超市-光復店 886-3-5729570
勝特力電子(上海) 86-21-34970699
勝特力電子(深圳) 86-755-83298787
<http://www.100y.com.tw>

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	S	source		
3	D	drain	 SC-70 (SOT323)	

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
2N7002BKW	SC-70	plastic, surface-mounted package; 3 leads; 1.3 mm pitch; 2 mm x 1.25 mm x 0.95 mm body	SOT323

7. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
2N7002BKW	X9%

[1] % = placeholder for manufacturing site code

8. Limiting values

Table 5. Limiting values

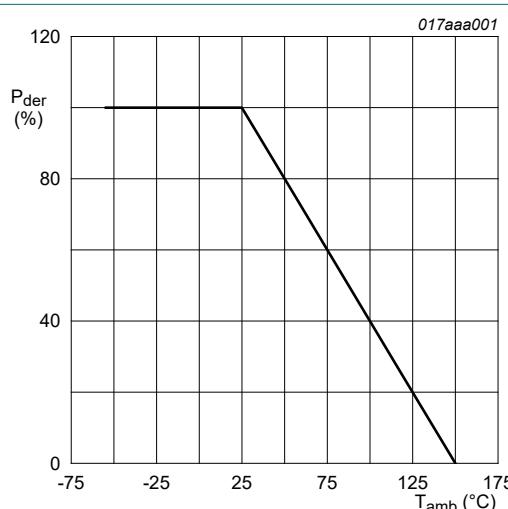
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{DS}	drain-source voltage	T _{amb} = 25 °C		-	60	V
V _{GS}	gate-source voltage			-20	20	V
I _D	drain current	V _{GS} = 10 V; T _{amb} = 25 °C	[1]	-	310	mA
		V _{GS} = 10 V; T _{amb} = 100 °C	[1]	-	215	mA
I _{DM}	peak drain current	T _{amb} = 25 °C; single pulse; t _p ≤ 10 µs		-	1.2	A
P _{tot}	total power dissipation	T _{amb} = 25 °C	[2]	-	275	mW
		T _{sp} = 25 °C	[1]	-	330	mW
				-	880	mW
T _j	junction temperature			-	150	°C
T _{amb}	ambient temperature			-55	150	°C
T _{stg}	storage temperature			-65	150	°C
Source-drain diode						
I _S	source current	T _{amb} = 25 °C	[1]	-	310	mA
ESD maximum rating						
V _{ESD}	electrostatic discharge voltage	HBM	[3]	-	2	kV

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm².

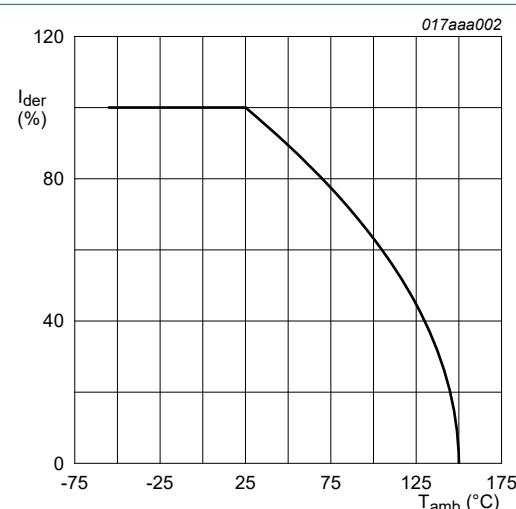
[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[3] Measured between all pins.



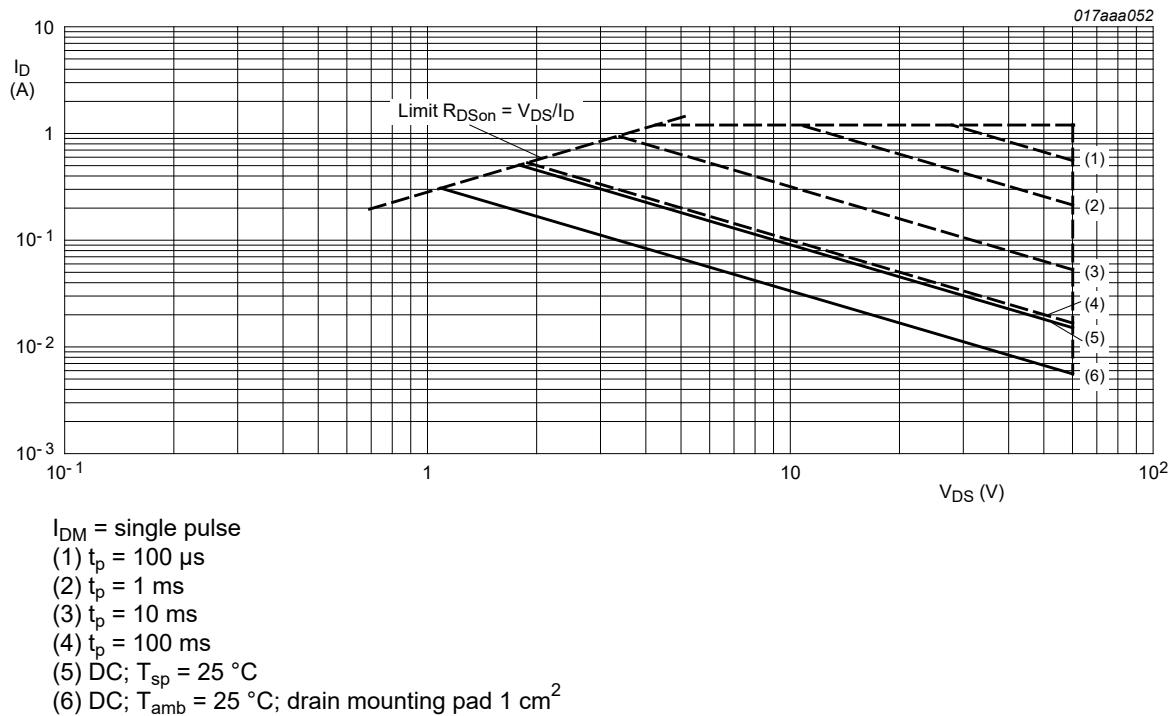
$$P_{der} = \frac{P_{tot}}{P_{tot}(25^\circ\text{C})} \times 100 \%$$

Fig. 1. Normalized total power dissipation as a function of ambient temperature



$$I_{der} = \frac{I_D}{I_D(25^\circ\text{C})} \times 100 \%$$

Fig. 2. Normalized continuous drain current as a function of ambient temperature



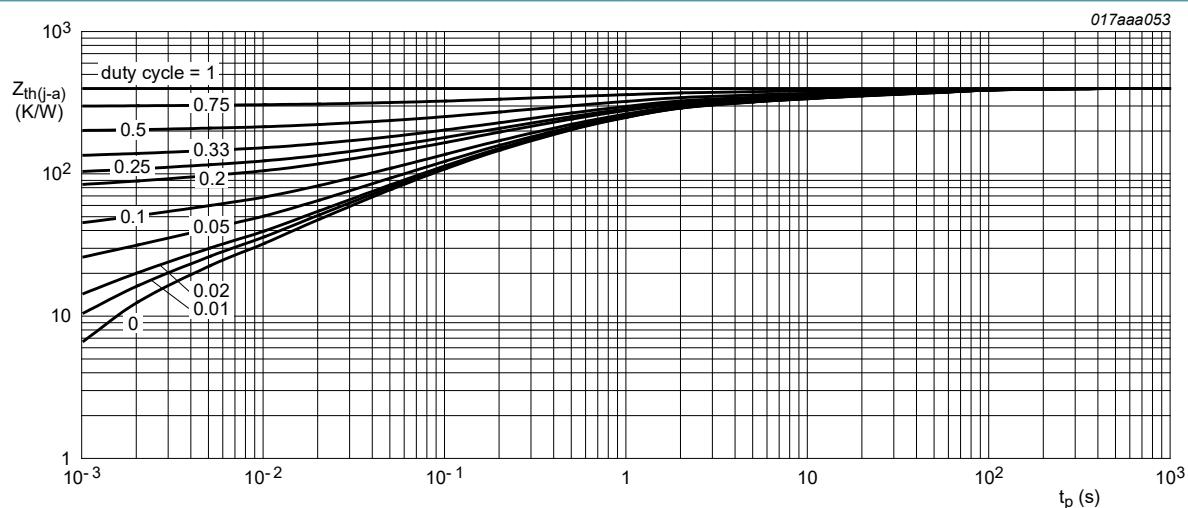
9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	395	455	K/W
			[2]	-	330	380	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	-	140	K/W

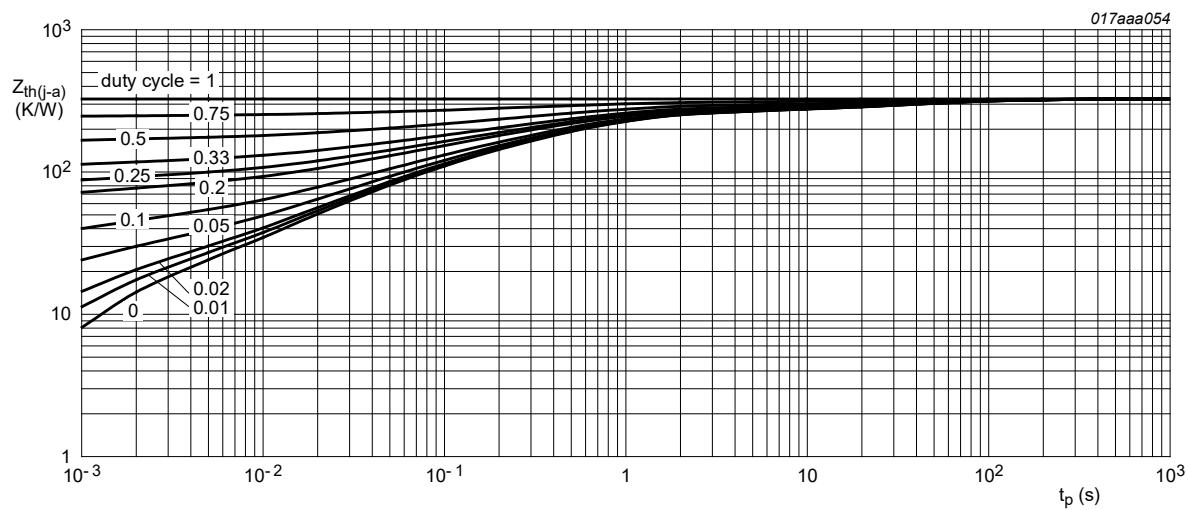
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm².



FR4 PCB, standard footprint

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



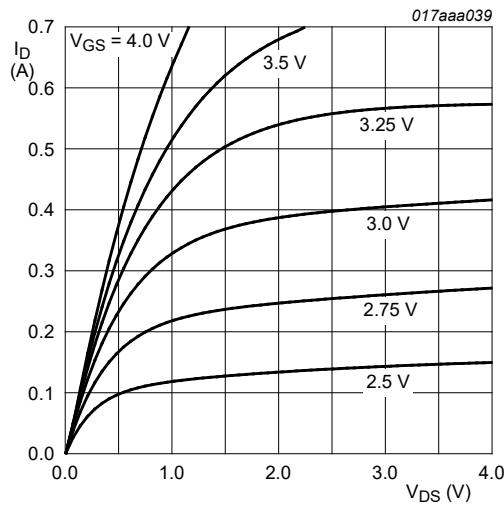
FR4 PCB, mounting pad for drain 1 cm²

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

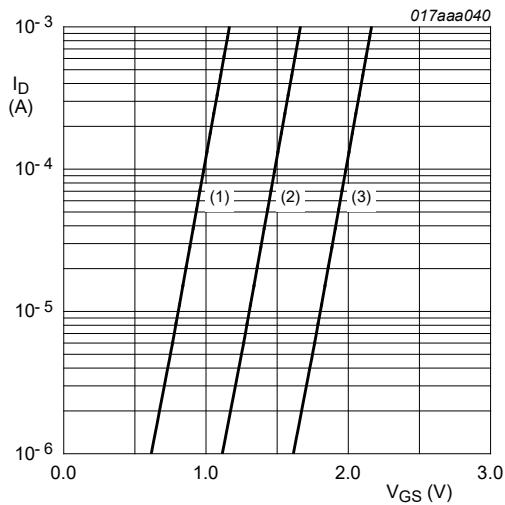
Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 10 \mu A$; $V_{GS} = 0 V$; $T_j = 25^\circ C$		60	-	-	V
V_{GSth}	gate-source threshold voltage	$I_D = 250 \mu A$; $V_{DS} = V_{GS}$; $T_j = 25^\circ C$		1.1	1.6	2.1	V
I_{DSS}	drain leakage current	$V_{DS} = 60 V$; $V_{GS} = 0 V$; $T_j = 25^\circ C$		-	-	1	μA
		$V_{DS} = 60 V$; $V_{GS} = 0 V$; $T_j = 150^\circ C$		-	-	10	μA
I_{GSS}	gate leakage current	$V_{GS} = 20 V$; $V_{DS} = 0 V$; $T_j = 25^\circ C$		-	-	10	μA
		$V_{GS} = -20 V$; $V_{DS} = 0 V$; $T_j = 25^\circ C$		-	-	10	μA
R_{DSon}	drain-source on-state resistance	$V_{GS} = 5 V$; $I_D = 50 mA$; $t_p \leq 300 \mu s$; $\delta \leq 0.01$; $T_j = 25^\circ C$		-	1.3	2	Ω
		$V_{GS} = 10 V$; $I_D = 500 mA$; $t_p \leq 300 \mu s$; $\delta \leq 0.01$; $T_j = 25^\circ C$		-	1	1.6	Ω
g_{fs}	forward transconductance	$V_{DS} = 10 V$; $I_D = 200 mA$; $t_p \leq 300 \mu s$; $\delta \leq 0.01$; $T_j = 25^\circ C$		-	550	-	mS
Dynamic characteristics							
$Q_{G(tot)}$	total gate charge	$V_{DS} = 30 V$; $I_D = 300 mA$; $V_{GS} = 4.5 V$; $T_j = 25^\circ C$		-	0.5	0.6	nC
Q_{GS}	gate-source charge			-	0.2	-	nC
Q_{GD}	gate-drain charge			-	0.1	-	nC
C_{iss}	input capacitance	$V_{DS} = 10 V$; $f = 1 MHz$; $V_{GS} = 0 V$; $T_j = 25^\circ C$		-	33	50	pF
C_{oss}	output capacitance			-	7	-	pF
C_{rss}	reverse transfer capacitance			-	4	-	pF
$t_{d(on)}$	turn-on delay time			-	5	10	ns
t_r	rise time	$V_{DS} = 50 V$; $R_L = 250 \Omega$; $V_{GS} = 10 V$; $R_{G(ext)} = 6 \Omega$; $T_j = 25^\circ C$		-	6	-	ns
$t_{d(off)}$	turn-off delay time			-	12	24	ns
t_f	fall time			-	7	-	ns
Source-drain diode							
V_{SD}	source-drain voltage	$I_S = 115 mA$; $V_{GS} = 0 V$; $T_j = 25^\circ C$		0.47	0.75	1.1	V



$T_{amb} = 25^\circ\text{C}$

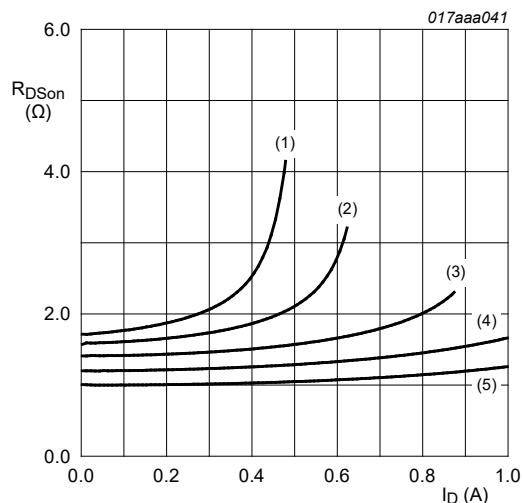
Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values



$T_{amb} = 25^\circ\text{C}; V_{DS} = 5\text{ V}$

- (1) minimum values
- (2) typical values
- (3) maximum values

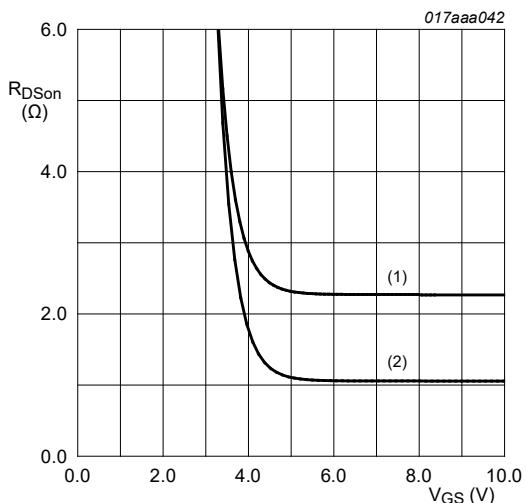
Fig. 7. Sub-threshold drain current as a function of gate-source voltage



$T_{amb} = 25^\circ\text{C}$

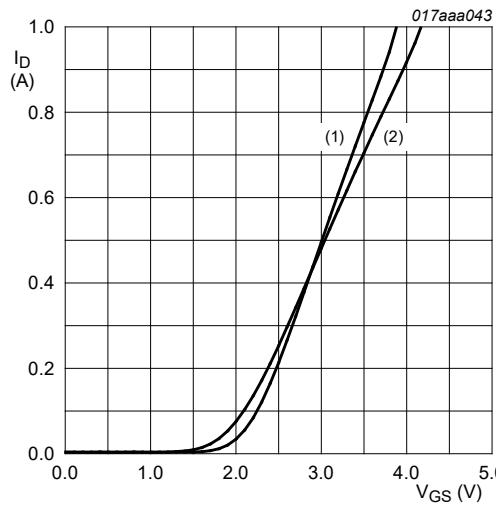
- (1) $V_{GS} = 3.25\text{ V}$
- (2) $V_{GS} = 3.5\text{ V}$
- (3) $V_{GS} = 4\text{ V}$
- (4) $V_{GS} = 5\text{ V}$
- (5) $V_{GS} = 10\text{ V}$

Fig. 8. Drain-source on-state resistance as a function of drain current; typical values



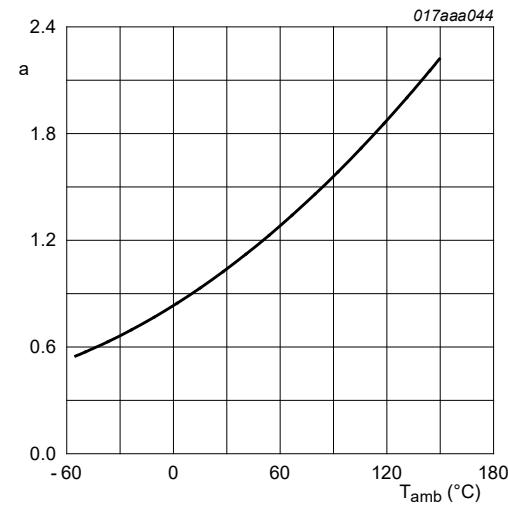
$I_D = 500\text{ mA}$
 (1) $T_{amb} = 150^\circ\text{C}$
 (2) $T_{amb} = 25^\circ\text{C}$

Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values



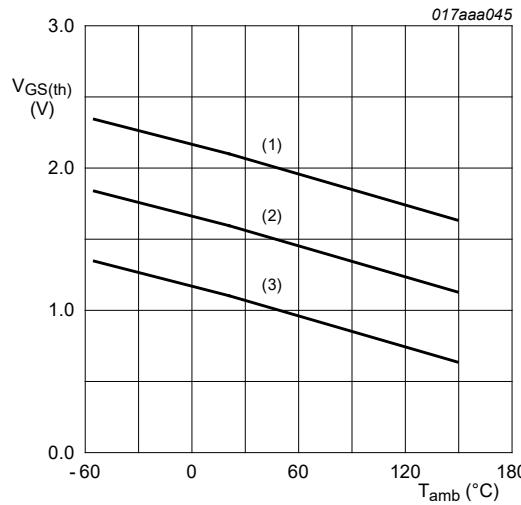
$V_{DS} > I_D \times R_{DSon}$
 (1) $T_j = 25^\circ\text{C}$
 (2) $T_j = 150^\circ\text{C}$

Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values



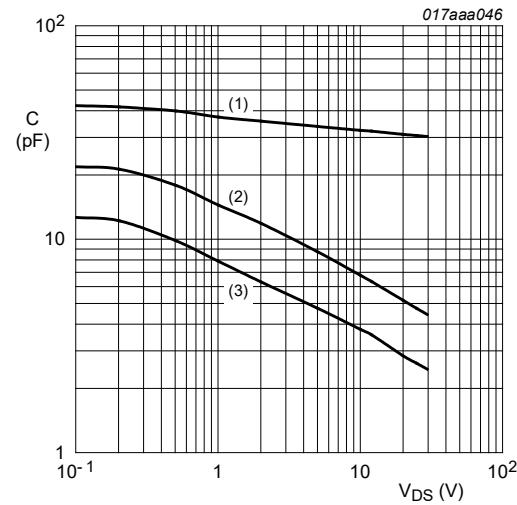
$$a = \frac{R_{DSon}}{R_{DSon}(25^\circ\text{C})}$$

Fig. 11. Normalized drain-source on-state resistance as a function of ambient temperature; typical values



$I_D = 0.25 \text{ mA}; V_{DS} = V_{GS}$
 (1) maximum values
 (2) typical values
 (3) minimum values

Fig. 12. Gate-source threshold voltage as a function of ambient temperature



$f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}$
 (1) C_{iss}
 (2) C_{oss}
 (3) C_{rss}

Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

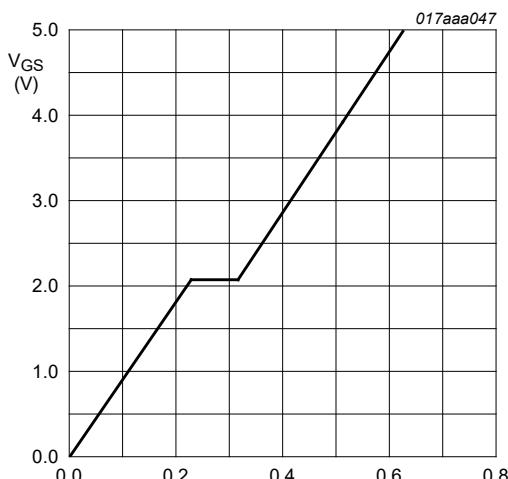


Fig. 14. Gate-source voltage as a function of gate charge; typical values

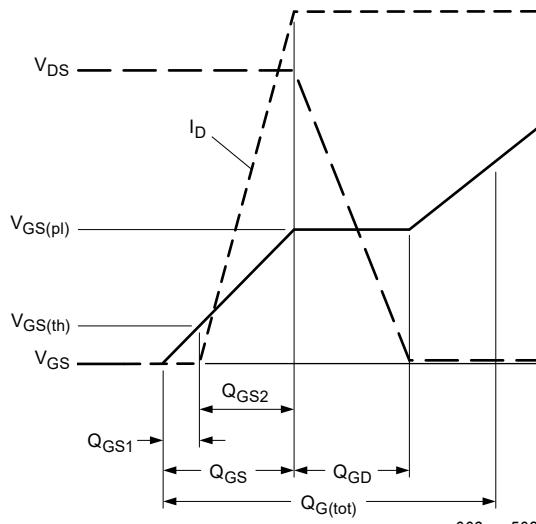


Fig. 15. Gate charge waveform definitions

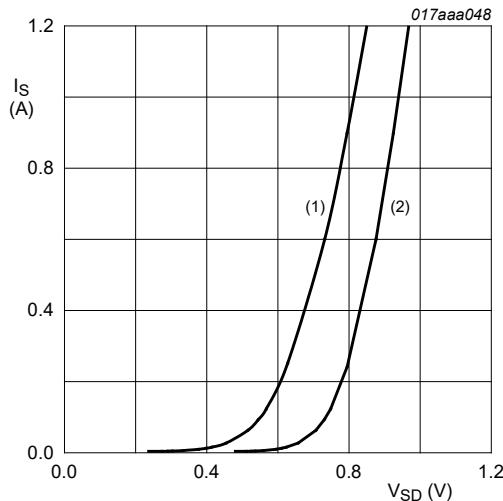


Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information

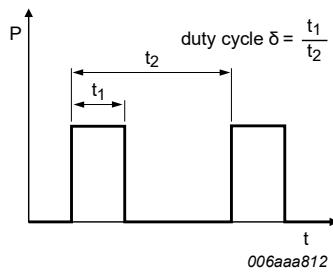


Fig. 17. Duty cycle definition

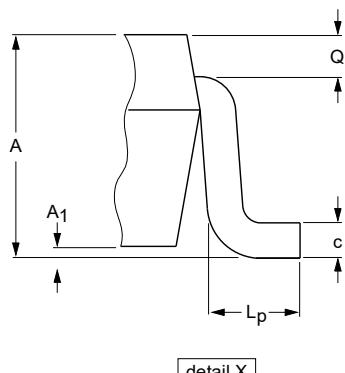
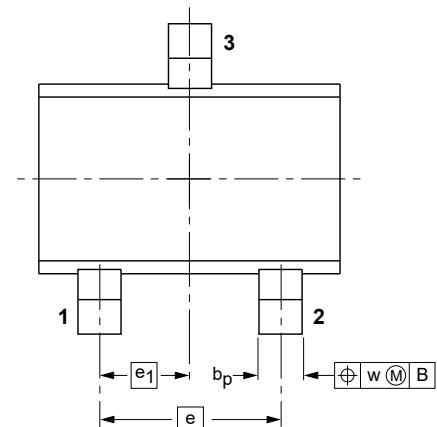
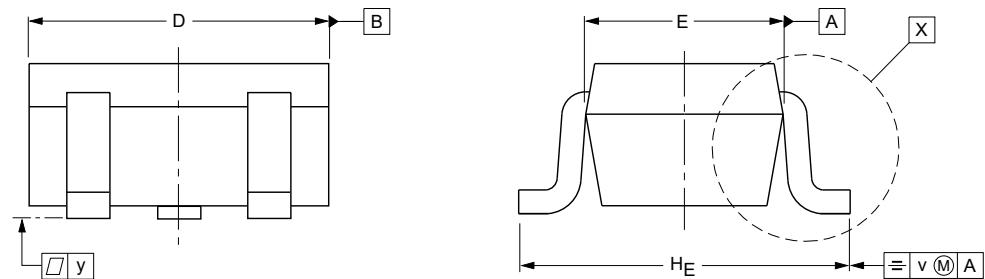
Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

Plastic surface-mounted package; 3 leads

SOT323



0 1 2 mm
scale

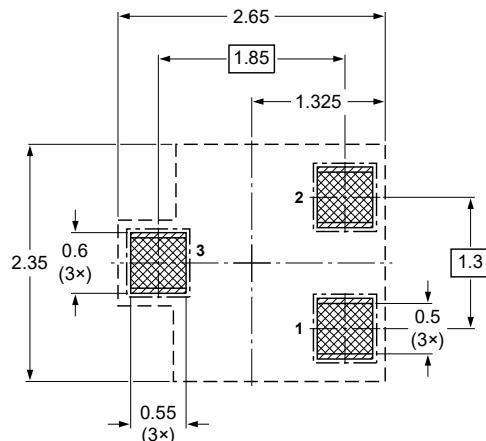
DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT323			SC-70			04-11-04 06-03-16

Fig. 18. Package outline SC-70 (SOT323)

13. Soldering



solder lands

solder resist

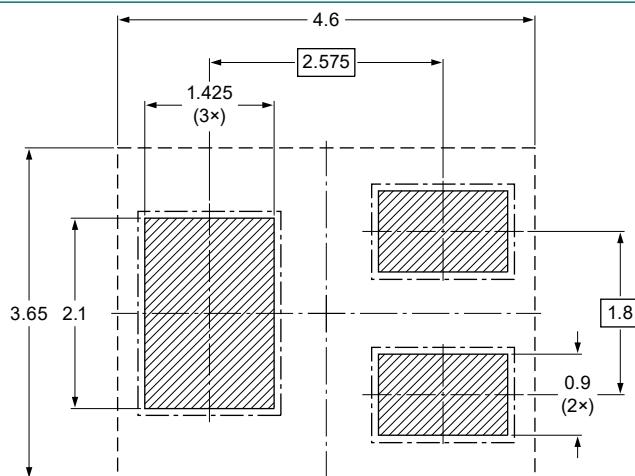
solder paste

occupied area

Dimensions in mm

sot323_fr

Fig. 19. Reflow soldering footprint for SC-70 (SOT323)



solder lands

solder resist

occupied area

Dimensions in mm

preferred transport
direction during soldering

sot323_fw

Fig. 20. Wave soldering footprint for SC-70 (SOT323)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
2N7002BKW v.2	20241017	Product data sheet	-	2N7002BKW v.1
Modifications:	<ul style="list-style-type: none">Chapter "Characteristics": Conditions corrected for parameters $t_{d(on)}$, t_r, $t_{d(off)}$, t_fChapter "Characteristics": Conditions corrected for Fig. 14			
2N7002BKW v.1	20100617	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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